

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	350	425/128.col.s.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/01/08 11:52
L4	17327	257/787.col.s. 257/ e21.502.col.s. 257/ e21.504.col.s. 257/ e21.705.col.s. 257/ e23.116.col.s. 257/ e23.125.col.s. 438/108. col.s. 438/124.col.s. 438/126.col.s. 438/127.col.s. 156/500.col.s. 425/117.col.s. 425/125.col.s. 425/128.col.s.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/01/08 11:54
L5	372	L4 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed\$6 assembl\$6) same (edge project\$6) same (movable displac\$6 support receiv\$6 force part))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2009/01/08 11:54
L6	408	(encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open\$6) same (feed\$6 assembl\$6) same (edge project\$6)	US-PGPUB; USPAT	OR	ON	2009/01/08 12:07

		same (mov\$6 displac\$6 adjust\$6) same (support receiv\$6 force part)				
L7	226	(encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (mov\$6 displac\$6 adjust\$6) and (support receiv\$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/08 12:13

1/8/09 12:19:07 PM

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